

Figure 2. Pin Configuration (Top View)

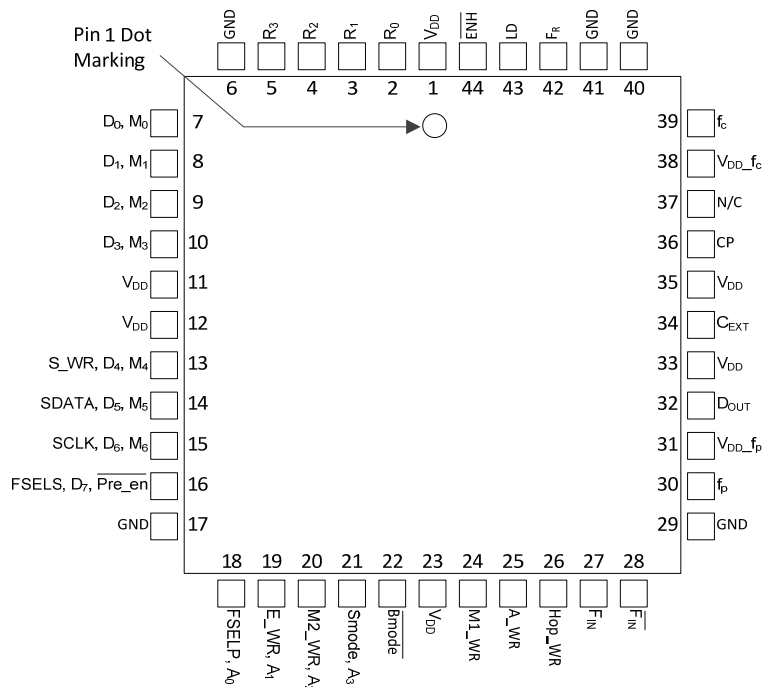


Figure 3. Package Type
44-lead CQFJ

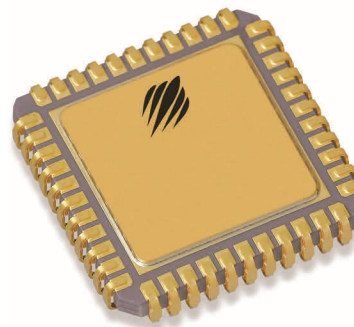


Table 1. Pin Descriptions

Pin No.	Pin Name	Interface Mode	Type	Description
1	V _{DD}	ALL	Note 1	Power supply input. Input may range from 2.85V to 3.15V. Bypassing recommended.
2	R ₀	Direct	Input	R counter bit0 (LSB).
3	R ₁	Direct	Input	R counter bit1.
4	R ₂	Direct	Input	R counter bit2.
5	R ₃	Direct	Input	R counter bit3.
6	GND	ALL	Note 1	Ground.
7	D ₀	Parallel	Input	Parallel data bus bit0 (LSB).
	M ₀	Direct	Input	M counter bit0 (LSB).
8	D ₁	Parallel	Input	Parallel data bus bit1.
	M ₁	Direct	Input	M counter bit1.
9	D ₂	Parallel	Input	Parallel data bus bit2.
	M ₂	Direct	Input	M counter bit2.
10	D ₃	Parallel	Input	Parallel data bus bit3.
	M ₃	Direct	Input	M counter bit3.
11	V _{DD}	ALL	Note 1	Same as pin 1.
12	V _{DD}	ALL	Note 1	Same as pin 1.
13	S_WR	Serial	Input	Serial load enable input. While S_WR is "low", SDATA can be serially clocked. Primary register data is transferred to the secondary register on S_WR or Hop_WR rising edge.
	D ₄	Parallel	Input	Parallel data bus bit4.
	M ₄	Direct	Input	M counter bit4.

Table 1. Pin Descriptions (continued)

Pin No.	Pin Name	Interface Mode	Type	Description
14	SDATA	Serial	Input	Binary serial data input. Input data entered MSB first.
	D ₅	Parallel	Input	Parallel data bus bit5.
	M ₅	Direct	Input	M counter bit5.
15	SCLK	Serial	Input	Serial clock input. SDATA is clocked serially into the 20-bit primary register (E_WR “low”) or the 8-bit enhancement register (E_WR “high”) on the rising edge of SCLK.
	D ₆	Parallel	Input	Parallel data bus bit6.
	M ₆	Direct	Input	M counter bit6.
16	FSELS	Serial	Input	Selects contents of primary register (FSELS=1) or secondary register (FSELS=0) for programming of internal counters while in serial interface mode.
	D ₇	Parallel	Input	Parallel data bus bit7 (MSB).
	Pre_en	Direct	Input	Prescaler enable, active “low”. When “high”, F _{in} bypasses the prescaler.
17	GND	ALL		Ground.
18	FSELP	Parallel	Input	Selects contents of primary register (FSELP=1) or secondary register (FSELP=0) for programming of internal counters while in parallel interface mode.
	A ₀	Direct	Input	A counter bit0 (LSB).
19	E_WR	Serial	Input	Enhancement register write enable. While E_WR is “high”, SDATA can be serially clocked into the enhancement register on the rising edge of SCLK.
		Parallel	Input	Enhancement register write. D[7:0] are latched into the enhancement register on the rising edge of E_WR.
	A ₁	Direct	Input	A counter bit1.
20	M2_WR	Parallel	Input	M2 write. D[3:0] are latched into the primary register (R[5:4], M[8:7]) on the rising edge of M2_WR.
	A ₂	Direct	Input	A counter bit2.
21	Smode	Serial, Parallel	Input	Selects serial bus interface mode (Bmode=0, Smode=1) or Parallel Interface mode (Bmode=0, Smode=0).
	A ₃	Direct	Input	A counter bit3 (MSB).
22	Bmode	ALL	Input	Selects direct interface mode (Bmode=1).
23	V _{DD}	ALL	Note 1	Same as pin 1.
24	M1_WR	Parallel	Input	M1 write. D[7:0] are latched into the primary register (Pre_en, M[6:0]) on the rising edge of M1_WR.
25	A_WR	Parallel	Input	A write. D[7:0] are latched into the primary register (R[3:0], A[3:0]) on the rising edge of A_WR.
26	Hop_WR	Serial, Parallel	Input	Hop write. The contents of the primary register are latched into the secondary register on the rising edge of Hop_WR.
27	F _{IN}	ALL	Input	Prescaler input from the VCO. 3.0 GHz max frequency.
28	F _{IN}	ALL	Input	Prescaler complementary input. A bypass capacitor in series with a 51Ω resistor should be placed as close as possible to this pin and be connected directly to the ground plane.
29	GND	ALL		Ground.
30	f _p	ALL	Output	Monitor pin for main divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V _{DD} pin 31.

Table 1. Pin Descriptions (continued)

Pin No.	Pin Name	Interface Mode	Type	Description
31	V_{DD-f_p}	ALL	Note 1	V_{DD} for f_p
32	D_{OUT}	Serial, Parallel	Output	Data Out. The MSEL signal and the raw prescaler output are available on D_{OUT} through enhancement register programming.
33	V_{DD}	ALL	Note 1	Same as pin 1.
34	C_{EXT}	ALL	Output	Logical "OR" of $PD_{\bar{U}}$ and $PD_{\bar{D}}$ terminated through an on chip, 2 k Ω series resistor. Connecting C_{EXT} to an external capacitor will low pass filter the input to the inverting amplifier used for driving LD.
35	V_{DD}	ALL	Note 1	Same as pin 1.
36	CP	ALL	Output	Charge pump current is sourced for "up" when f_c leads f_p and synced for "down" when f_c lags f_p .
37	NC	ALL		No connection.
38	V_{DD-f_c}	ALL	Note 1	V_{DD} for f_c
39	f_c	ALL	Output	Monitor pin for reference divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V_{DD} pin 38.
40	GND	ALL		Ground.
41	GND	ALL		Ground.
42	f_r	ALL	Input	Reference frequency input.
43	LD	ALL	Output, OD	Lock detect and open drain logical inversion of C_{EXT} . When the loop is in lock, LD is high impedance, otherwise LD is a logic low ("0").
44	$\overline{ENH}$	Serial, Parallel	Input	Enhancement mode. When asserted low ("0"), enhancement register bits are functional.

Notes: 1. V_{DD} pins 1, 11, 12, 23, 31, 33, 35 and 38 are connected by diodes and must be supplied with the same positive voltage level. V_{DD} pins 31 and 38 are used to enable test modes and should be left floating.
2. All digital input pins have 70 k Ω pull-down resistors to ground.

Table 2. Absolute Maximum Ratings

Symbol	Parameter/Condition	Min	Max	Unit
V_{DD}	Supply voltage	-0.3	4.0	V
V_I	Voltage on any input	-0.3	$V_{DD} + 0.3$	V
I_I	DC into any input	-10	+10	mA
I_O	DC into any output	-10	+10	mA
T_{STG}	Storage temperature range	-65	150	°C

Table 3. Operating Ratings

Symbol	Parameter/Condition	Min	Max	Unit
V_{DD}	Supply voltage	2.85	3.15	V
T_A	Operating ambient temperature range	-40	85	°C

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ratings table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Table 4. ESD Ratings

Symbol	Parameter/Condition	Level	Unit
V_{ESD}	ESD voltage (Human Body Model)*	1000	V

Note: * Periodically sampled, not 100% tested. Tested per MIL-STD-883, M3015 C2.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating in *Table 4*.

Latch-Up Immunity

Unlike conventional CMOS devices, UltraCMOS devices are immune to latch-up.

ELDRS

UltraCMOS devices do not include bipolar minority carrier elements and therefore do not exhibit enhanced low dose rate sensitivity.

Table 5. DC Characteristics: $V_{DD} = 3.0V$, $-40\text{ }^{\circ}\text{C} < T_A < +85\text{ }^{\circ}\text{C}$, unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I_{DD}	Operational supply current; Prescaler disabled Prescaler enabled	$V_{DD} = 2.85$ to $3.15V$		10 24	31	mA mA
Digital inputs: all except f_r, F_{IN}, $\overline{F_{IN}}$						
V_{IH}	High level input voltage	$V_{DD} = 2.85$ to $3.15V$	$0.7 \times V_{DD}$			V
V_{IL}	Low level input voltage	$V_{DD} = 2.85$ to $3.15V$			$0.3 \times V_{DD}$	V
I_{IH}	High level input current	$V_{IH} = V_{DD} = 3.15V$			+70	μA
I_{IL}	Low level input current	$V_{IL} = 0$, $V_{DD} = 3.15V$	-1			μA
Reference divider input: f_r						
I_{IHR}	High level input current	$V_{IH} = V_{DD} = 3.15V$			+100	μA
I_{ILR}	Low level input current	$V_{IL} = 0$, $V_{DD} = 3.15V$	-100			μA
R0 input: R_0						
I_{IHRO}	High level input current	$V_{IH} = V_{DD} = 3.15V$			+70	μA
I_{ILRO}	Low level input current	$V_{IL} = 0$, $V_{DD} = 3.15V$	-5			μA
Counter and phase detector outputs: f_c, f_p						
V_{OLD}	Output voltage LOW	$I_{out} = 6\text{ mA}$			0.4	V
V_{OHD}	Output voltage HIGH	$I_{out} = -3\text{ mA}$	$V_{DD} - 0.4$			V
Lock detect outputs: C_{EXT}, LD						
V_{OLC}	Output voltage LOW, C_{EXT}	$I_{out} = 100\text{ }\mu A$			0.4	V
V_{OHC}	Output voltage HIGH, C_{EXT}	$I_{out} = -100\text{ }\mu A$	$V_{DD} - 0.4$			V
V_{OLLD}	Output voltage LOW, LD	$I_{out} = 6\text{ mA}$			0.4	V
Charge pump output: CP						
$I_{CP} - \text{source}$	Drive current	$V_{CP} = V_{DD} / 2$	-2.6	-2	-1.4	mA
$I_{CP} - \text{sink}$	Drive current	$V_{CP} = V_{DD} / 2$	1.4	2	2.6	mA
I_{CPL}	Leakage current	$1.0\text{ V} < V_{CP} < V_{DD} - 1.0V$	-1		1	μA
$I_{CP} - \text{source}$ vs. $I_{CP} - \text{sink}$	Sink vs. source mismatch	$V_{CP} = V_{DD} / 2$, $T_A = 25\text{ }^{\circ}\text{C}$			25	%
I_{CP} vs. V_{CP}	Output current magnitude variation vs. voltage	$V < V_{CP} < V_{DD} - 1.0V$ $T_A = 25\text{ }^{\circ}\text{C}$			25	%

Table 6. AC Characteristics: $V_{DD} = 3.0V$, $-40\text{ }^{\circ}C < T_A < +85\text{ }^{\circ}C$, unless otherwise specified

Symbol	Parameter	Condition	Min	Max	Unit
Control interface and latches (see Figures 4–6)					
f_{CLK}	Serial data clock frequency	Note 1		10	MHz
t_{CLKH}	Serial clock HIGH time		30		ns
t_{CLKL}	Serial clock LOW time		30		ns
t_{DSU}	SDATA hold time after SCLK rising edge, D[7:0] set-up time to M1_WR, M2_WR, A_WR, E_WR rising edge		10		ns
t_{DHLD}	SDATA hold time after SCLK rising edge, D[7:0] hold time to M1_WR, M2_WR, A_WR, E_WR rising edge		10		ns
t_{PW}	S_WR, M1_WR, M2_WR, A_WR, E_WR pulse width		30		ns
t_{CWR}	SCLK rising edge to S_WR rising edge. S_WR, M1_WR, M2_WR, A_WR falling edge to Hop_WR rising edge		30		ns
t_{CE}	SCLK falling edge to E_WR transition		30		ns
t_{WRC}	S_WR falling edge to Sclk rising edge. Hop_WR falling edge to S_WR, M1_WR, M2_WR, A_WR rising edge		30		ns
t_{EC}	E_WR transition to SCLK rising edge		30		ns
t_{MDO}	MSEL data out delay after F_{IN} rising edge	$C_L = 12\text{ pf}$		8	ns
Main divider (prescaler enabled)					
F_{IN}	Operating frequency		500	3000	MHz
P_{F_IN}	Input level range	External AC coupling	–5	5	dBm
Main divider (prescaler bypassed)					
F_{IN}	Operating frequency		50	300	MHz
P_{F_IN}	Input level range	External AC coupling	–5	5	dBm
Reference divider					
f_r	Operating frequency	Note 3		100	MHz
P_{fr}	Reference input power (Note 2)	Single-ended input	–2		dBm
Phase detector					
f_c	Comparison frequency	Note 3		20	MHz

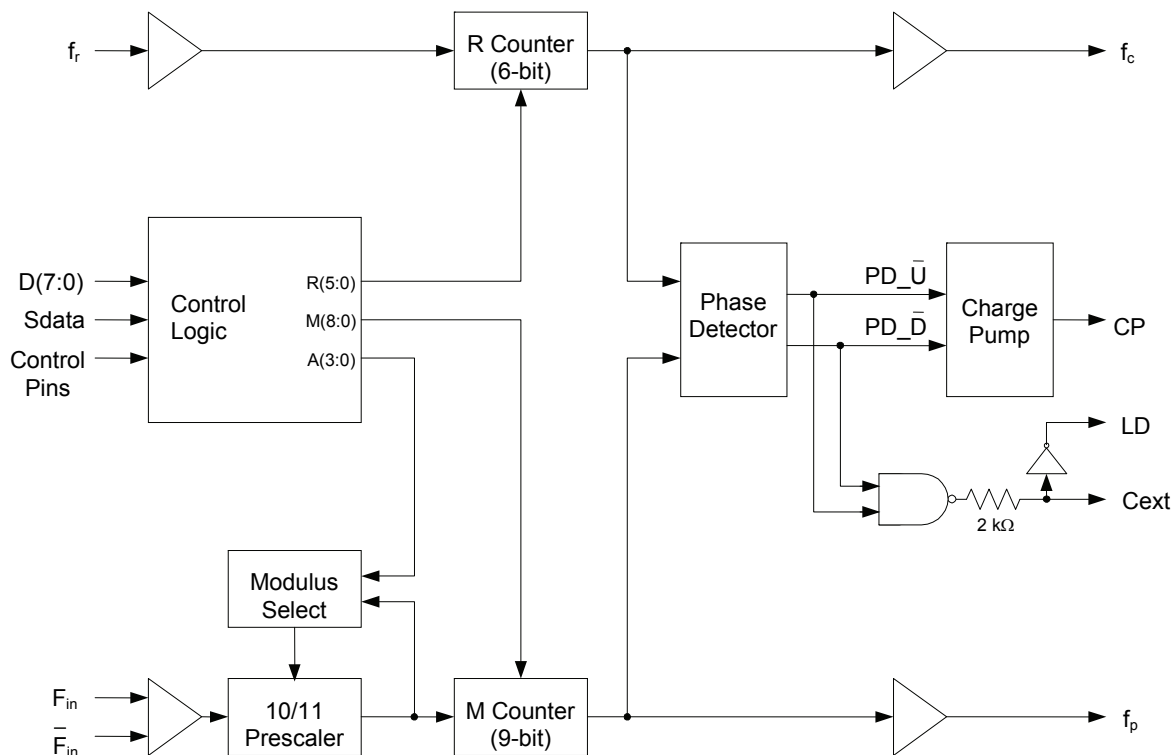
Notes: 1. f_{CLK} is verified during the functional pattern test. Serial programming sections of the functional pattern are clocked at 10 MHz to verify f_{CLK} specification.
2. CMOS logic levels can be used to drive reference input if DC coupled. Voltage input needs to be a minimum of 0.5 V_{p-p} .
3. Parameter is guaranteed through characterization only, and is not tested.

Functional Description

The PE9701 consists of a prescaler, counters, a phase detector, a charge pump, and control logic. The dual modulus prescaler divides the VCO frequency by either 10 or 11, depending on the value of the modulus select. Counters “R” and “M” divide the reference and prescaler output, respectively, by integer values stored in a 20-bit register. An additional counter (“A”) is used in the modulus select logic. The phase-frequency

detector generates up and down frequency control signals. The control logic includes a selectable chip interface. Data can be written via serial bus, parallel bus, or hardwired directly to the pins. There are also various operational and test modes and a lock detect output.

Figure 4. Functional Block Diagram



Main Counter Chain

Normal Operating Mode

The main counter chain divides the RF input frequency, F_{IN} , by an integer derived from the user-defined values in the “M” and “A” counters. It is composed of the 10/11 dual modulus prescaler, modulus select logic, and 9-bit M counter. Setting $\overline{\text{Pre_en}}$ “low” enables the 10/11 prescaler. Setting $\overline{\text{Pre_en}}$ “high” allows F_{IN} to bypass the prescaler and powers down the prescaler.

The output from the main counter chain, f_p , is related to the VCO frequency, F_{IN} , by the following equation:

$$f_p = F_{IN} / [10 \times (M+1) + A] \quad (1)$$

where $A \leq M+1$, $1 \leq M \leq 511$

When the loop is locked, F_{IN} is related to the reference frequency, f_r , by the following equation:

$$F_{IN} = [10 \times (M+1) + A] \times [F_R / (R+1)] \quad (2)$$

where $A \leq M+1$, $1 \leq M \leq 511$

A consequence of the upper limit on A is that F_{IN} must be greater than or equal to $90 \times [F_R / (R+1)]$ to obtain contiguous channels. Programming the M counter with the minimum value of “1” will result in a minimum M counter divide ratio of “2”. In Direct Interface mode, main counter inputs M_7 and M_8 are internally forced low. In this mode, the M value is limited to $1 \leq M \leq 127$.

Prescaler Bypass Mode

Setting $\overline{\text{Pre_en}}$ “high” allows F_{IN} to bypass and power down the prescaler. In this mode, the 10/11 prescaler and A register are not active, and the input VCO frequency is divided by the M counter directly. The following equation relates F_{IN} to the reference frequency, F_R :

$$F_{IN} = (M+1) \times [F_R / (R+1)] \quad (3)$$

where $1 \leq M \leq 511$

In Direct Interface mode, main counter inputs M_7 and M_8 are internally forced low. In this mode, the M value is limited to $1 \leq M \leq 127$.

Reference Counter

The reference counter chain divides the reference frequency, F_R , down to the phase detector comparison frequency, f_c .

The output frequency of the 6-bit R counter is related to the reference frequency by the following equation:

$$f_c = F_R / (R+1) \quad (4)$$

where $0 \leq R \leq 63$

Note that programming R with “0” will pass the reference frequency, F_R , directly to the phase detector.

In Direct Interface mode, R counter inputs R_4 and R_5 are internally forced low (“0”). In this mode, the R value is limited to $0 \leq R \leq 15$.

Register Programming

Parallel Interface Mode

Parallel Interface mode is selected by setting the $\overline{\text{Bmode}}$ input “low” and the $\overline{\text{Smode}}$ input “low”. Parallel input data, $D[7:0]$, is latched in a parallel fashion into one of three 8-bit primary register sections on the rising edge of $M1_WR$, $M2_WR$, or A_WR per the mapping shown in *Table 7*. The contents of the primary register are transferred into a secondary register on the rising edge of Hop_WR according to the timing diagram shown in *Figure 5*. Data is transferred to the counters as shown in *Table 7*.

The secondary register acts as a buffer to allow rapid changes to the VCO frequency. This double buffering for “ping-pong” counter control is programmed via the $\overline{\text{FSELP}}$ input. When $\overline{\text{FSELP}}$ is “high”, the primary register contents set the counter inputs. When $\overline{\text{FSELP}}$ is “low”, the secondary register contents are utilized. Parallel input data, $D[7:0]$, is latched into the enhancement register on the rising edge of $\overline{\text{E_WR}}$ according to the timing diagram shown in *Figure 5*. This data provides control bits as shown in *Table 8* with bit functionality enabled by asserting the $\overline{\text{ENH}}$ input “low.”

Serial Interface Mode

Serial Interface Mode is selected by setting the $\overline{\text{Bmode}}$ input “low” and the Smode input “high”.

While the E_WR input is “low” and the S_WR input is “low”, serial input data (SDATA input), B_0 to B_{19} , is clocked serially into the primary register on the rising edge of SCLK , MSB (B_0) first. The contents from the primary register are transferred into the secondary register on the rising edge of either S_WR or Hop_WR according to the timing diagram shown in *Figure 6*. Data is transferred to the counters as shown in *Table 7*.

The double buffering provided by the primary and secondary registers allows for “ping-pong” counter control using the FSELS input. When FSELS is “high”, the primary register contents set the counter inputs. When FSELS is “low”, the secondary register contents are utilized.

While the E_WR input is “high” and the S_WR input is “low”, serial input data (SDATA input), B_0 to B_7 , is clocked serially into the enhancement register on the rising edge of SCLK , MSB (B_0) first. The enhancement register is double buffered to prevent inadvertent control changes during serial loading, with buffer capture of the serially-entered data performed on the falling edge of E_WR according to the timing diagram shown in *Figure 6*. After the falling edge of E_WR , the data provides control bits as shown in *Table 8* with bit functionality enabled by asserting the $\overline{\text{ENH}}$ input “low”.

Direct Interface Mode

Direct Interface mode is selected by setting the $\overline{\text{Bmode}}$ input “high”.

Counter control bits are set directly at the pins as shown in *Table 7*. In Direct Interface mode, main counter inputs M_7 and M_8 , and R counter inputs R_4 and R_5 are internally forced low (“0”).

Table 7. Primary Register Programming

Interface Mode	$\overline{\text{ENH}}$	$\overline{\text{Bmode}}$	Smode	R_5	R_4	M_8	M_7	$\overline{\text{Pre_en}}$	M_6	M_5	M_4	M_3	M_2	M_1	M_0	R_3	R_2	R_1	R_0	A_3	A_2	A_1	A_0
Parallel	1	0	0	M2_WR rising edge load				M1_WR rising edge load								A_WR rising edge load							
				D_3	D_2	D_1	D_0	D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0	D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0
Serial*	1	0	1	B_0	B_1	B_2	B_3	B_4	B_5	B_6	B_7	B_8	B_9	B_{10}	B_{11}	B_{12}	B_{13}	B_{14}	B_{15}	B_{16}	B_{17}	B_{18}	B_{19}
Direct	1	1	X	0	0	0	0	$\overline{\text{Pre_en}}$	M_6	M_5	M_4	M_3	M_2	M_1	M_0	R_3	R_2	R_1	R_0	A_3	A_2	A_1	A_0

Note: * Serial data clocked serially on SCLK rising edge while E_WR “low” and captured in secondary register on S_WR rising edge.

↑ MSB (first in) (last in) LSB ↑

Table 8. Enhancement Register Programming

Interface Mode	$\overline{\text{ENH}}$	$\overline{\text{Bmode}}$	Smode	Reserved	Reserved	Reserved	Power down	Counter load	MSEL output	Prescaler output	f_c, f_p OE
Parallel	0	0	0	E_WR rising edge load							
				D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0
Serial*	0	0	1	B_0	B_1	B_2	B_3	B_4	B_5	B_6	B_7

Note: * Serial data clocked serially on SCLK rising edge while E_WR “high” and captured in the double buffer on E_WR falling edge.

↑ MSB (first in) (last in) LSB ↑

Figure 5. Parallel Interface Mode Timing Diagram

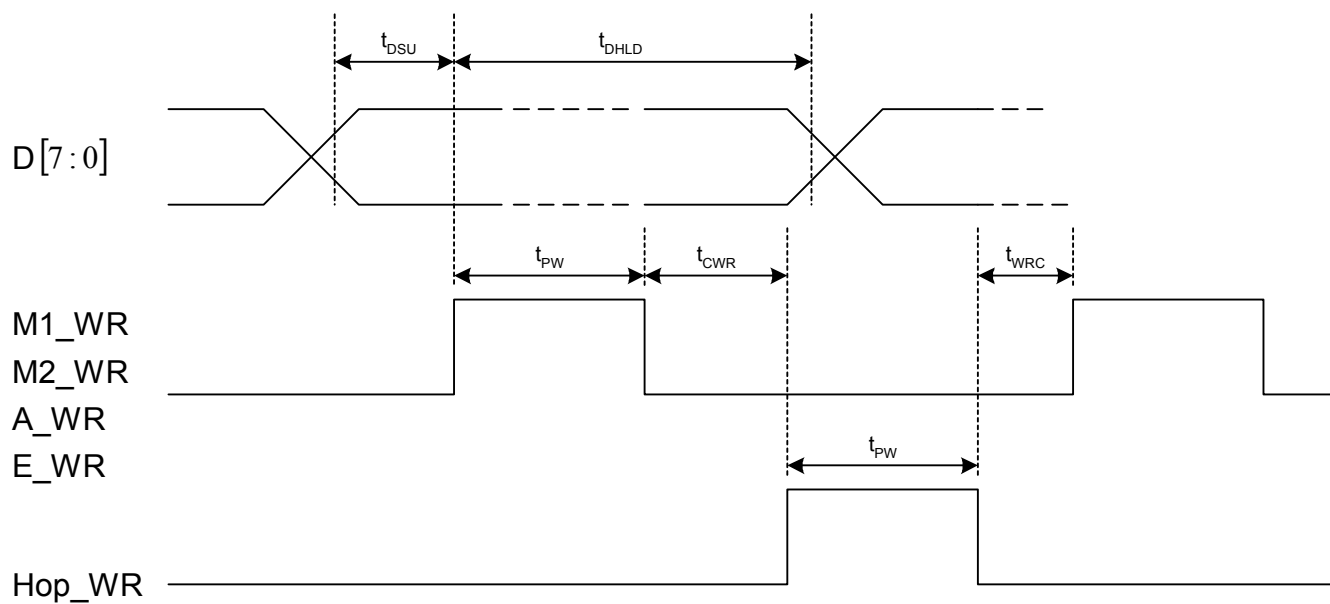
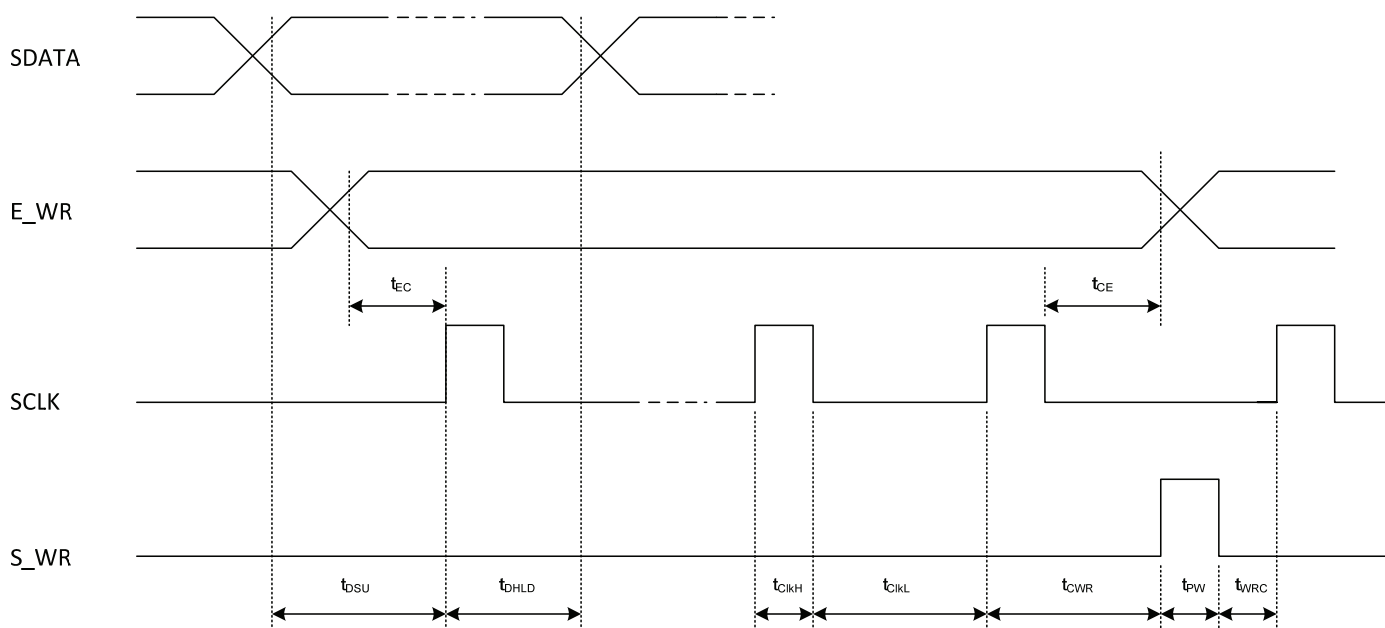


Figure 6. Serial Interface Mode Timing Diagram



Enhancement Register

The functions of the enhancement register bits are shown below with all bits active “high”.

Table 9. Enhancement Register Bit Functionality

Bit Function		Description
Bit 0	Reserved*	
Bit 1	Reserved*	
Bit 2	Reserved*	
Bit 3	Power down	Power down of all functions except programming interface.
Bit 4	Counter load	Immediate and continuous load of counter programming as directed by the $\overline{\text{Bmode}}$ and Smode inputs.
Bit 5	MSEL output	Drives the internal dual modulus prescaler modulus select (MSEL) onto the D_{OUT} output.
Bit 6	Prescaler output	Drives the raw internal prescaler output (f_{main}) onto the D_{OUT} output.
Bit 7	$\text{f}_p, \text{f}_c \overline{\text{OE}}$	f_p, f_c outputs disabled.

Note: * Program to 0.

Phase Detector

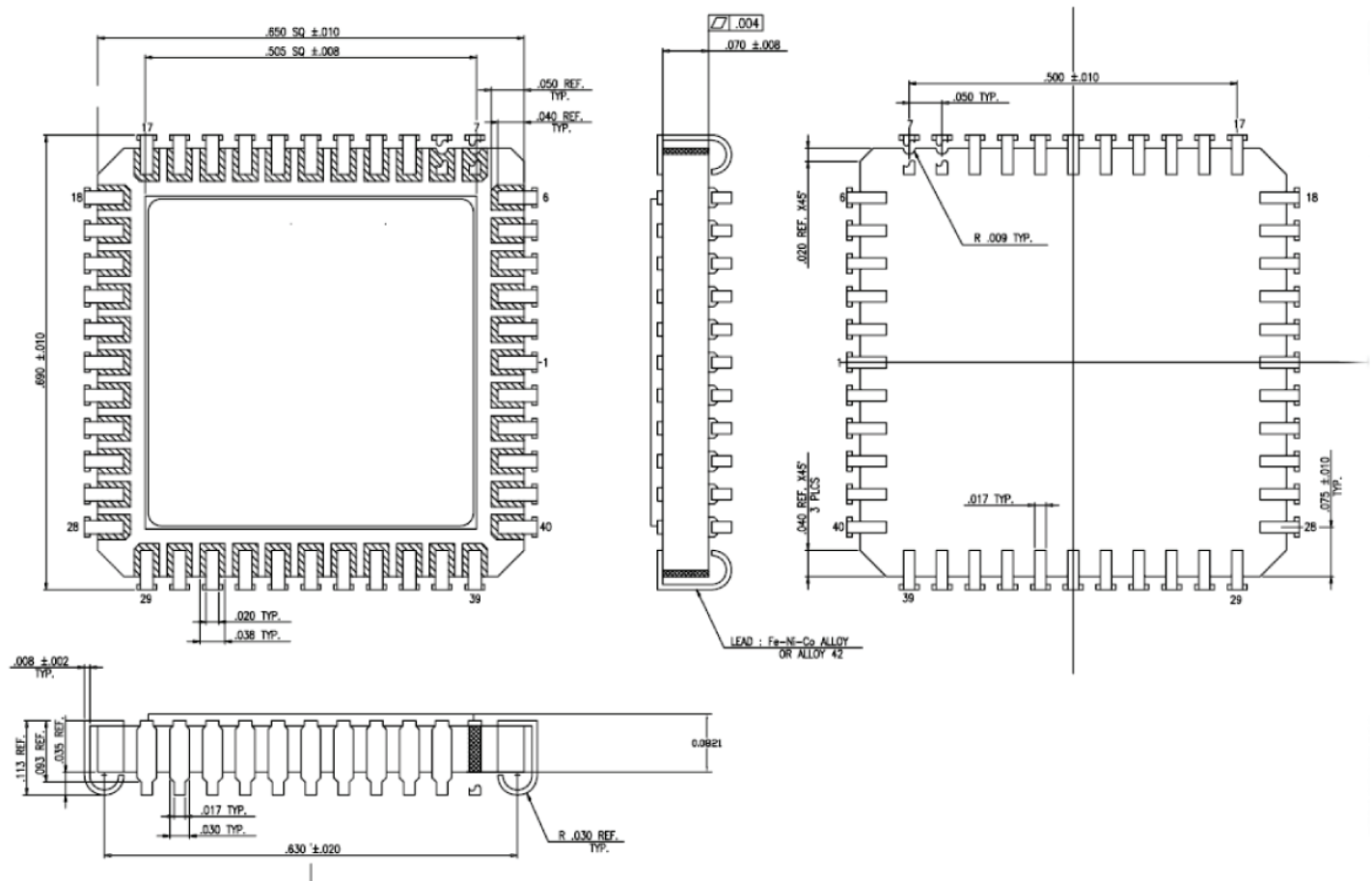
The phase detector is triggered by rising edges from the main Counter (f_p) and the reference counter (f_c). It has two outputs, namely PD_U , and PD_D . If the divided VCO leads the divided reference in phase or frequency (f_p leads f_c), PD_D pulses “high”. If the divided reference leads the divided VCO in phase or frequency (f_r leads f_p), PD_U pulses “high”. The width of either pulse is directly proportional to phase offset between the two input signals, f_p and f_c .

The signals from the phase detector couple directly to a charge pump. PD_U controls a current source at pin CP with constant amplitude and pulse duration approximately the same as PD_U . PD_D similarly drives a current sink at pin

CP. The current pulses from pin CP are low pass filtered externally and then connected to the VCO tune voltage. PD_U pulses result in a current source, which increases the VCO frequency; PD_D pulses result in a current sink, which decreases VCO frequency.

A lock detect output, LD is also provided, via the pin C_{EXT} . C_{EXT} is the logical “NAND” of PD_U and PD_D waveforms, which is driven through a series 2 k Ω resistor. Connecting C_{EXT} to an external shunt capacitor provides integration. C_{EXT} also drives the input of an internal inverting comparator with an open drain output. Thus LD is an “AND” function of PD_U and PD_D . See *Figure 4* for a schematic of this circuit.

Figure 7. Package Drawing
44-lead CQFJ



All dimensions are in inches

DOC-51819

Figure 8. Top Marking Specifications



PRT-18329

△ = Pin 1 indicator

9701-XX = Part number (XX will be specified by the PO and/or the assembly instructions)

YYWW = Date Code, last two digits of the year and work week

ZZZZZZZ = Lot Code (up to seven digits)

nnnnnnn = Serial number of the part (up to six digits)

Table 10. Ordering Information

Order Code	Description	Package	Shipping Method
9701-01*	Engineering samples	44-pin CQFJ	40 units / Tray
9701-11	Flight units	44-pin CQFJ	40 units / Tray
9701-00	Evaluation kit		1 / Box

Note: * The PE9701-01 devices are ES (Engineering Sample) prototype units intended for use as initial evaluation units for customers of the PE9701-11 flight units. The PE9701-01 device provides the same functionality and footprint as the PE9701-11 space qualified device, and intended for engineering evaluation only. They are tested at +25 °C only and processed to a non-compliant flow (e.g. No burn-in, non-hermetic, etc). These units are non-hermetic and are not suitable for qualification, production, radiation testing or flight use.

Sales Contact and Information

Contact Information:
e2v - <http://www.e2v-us.com> - inquiries @e2v-us.com

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